



Reflective multilayer coatings, an enabling component of Extreme Ultraviolet Lithography and beyond.....

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Carl Zeiss SMT GmbH, Germany



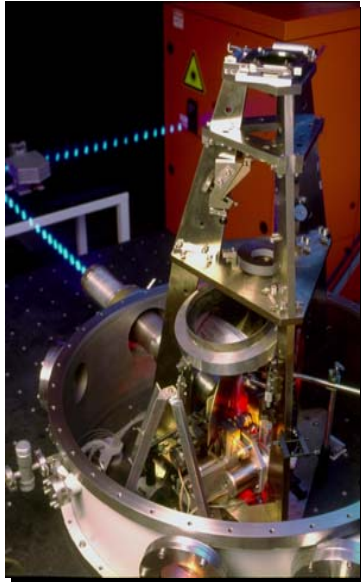
Outline

- Introduction
- Multilayer facilities at FOM and Carl Zeiss
- Multilayer development for EUV lithography
- Coatings on real optics
- Even shorter wavelength, Beyond EUV..... 6.x nm



EUVL: from basic research → *development labs*

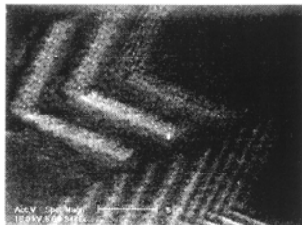
STW funded pilot research on lithographic imaging using 13.5 nm (1992)



Two prototype 13.5 nm wafer scanners (Alpha Demo Tools, ADT) in full operation at IMEC & CNSE (2006)



13.5 nm exposures in resist



λ	13.5 nm
NA	0.2
# Multilayer optics	10
Max diameter	45 cm
Resolution	~ diffraction limit



Deposition processes

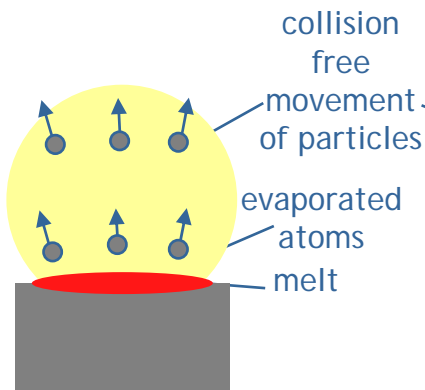
Energy of particles: main parameters responsible for balance between kinetics and thermodynamics in thin films

→ Need different energies at different stages of ML growth

E-beam evaporation

Thermal energy particles

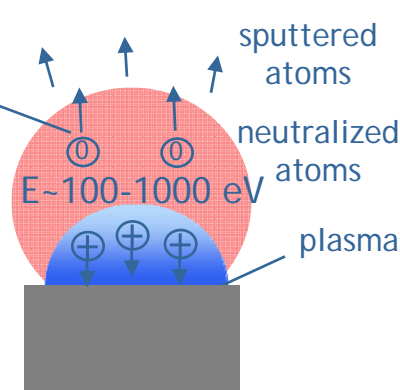
$E \sim 0.1 \text{ eV}$



Magnetron sputtering

High energy particles

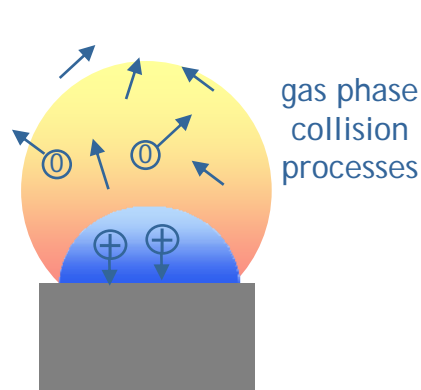
$E \sim 10 \text{ eV}$



Thermal Particle Magnetron*

Tunable energy particles

$E \ll 10 \text{ eV}$



Surface treatment

Surface



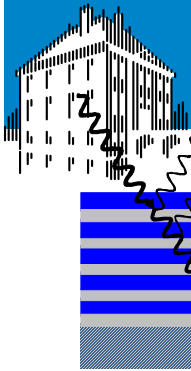
Ar^+, Kr^+

low energy ion bombardment
 $E \sim 10\text{-}50 \text{ eV}$

Thermal E particles: nucleate first monolayers

Higher energy particles: grow bulk layer

Ion bombardment: atom mobility, reconstruction, formation of compounds



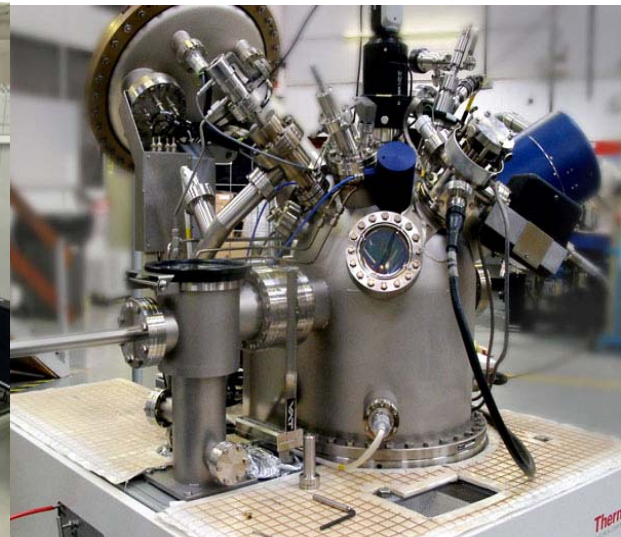
Deposition and analysis facilities @ FOM

- e-beam deposition
 - including ion beam polishing for layer smoothing
- magnetron sputtering (modified)



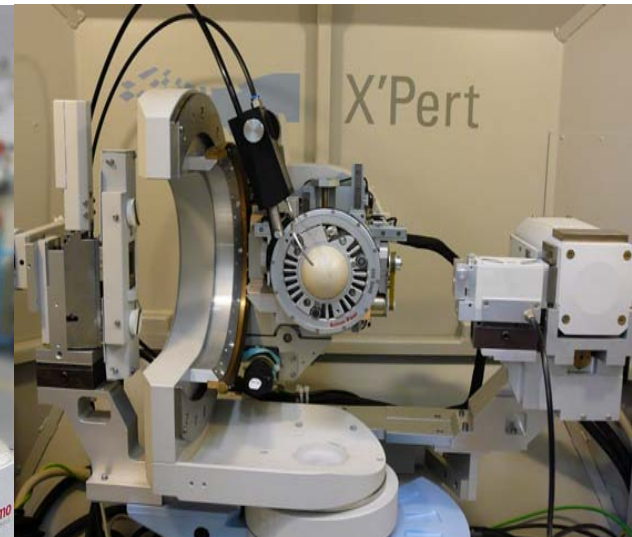
Coaters

- E-beam, Magnetron Sputtering



In-vacuo XPS, AES, STM

- Morphology, Chemical analysis.



Hard X-ray Diffractometer

- Multilayer structure
- Crystalline structure

...required for basic understanding of physics phenomena!



Deposition facilities @ Carl Zeiss



e-beam deposition

- including ion beam polishing for layer smoothening



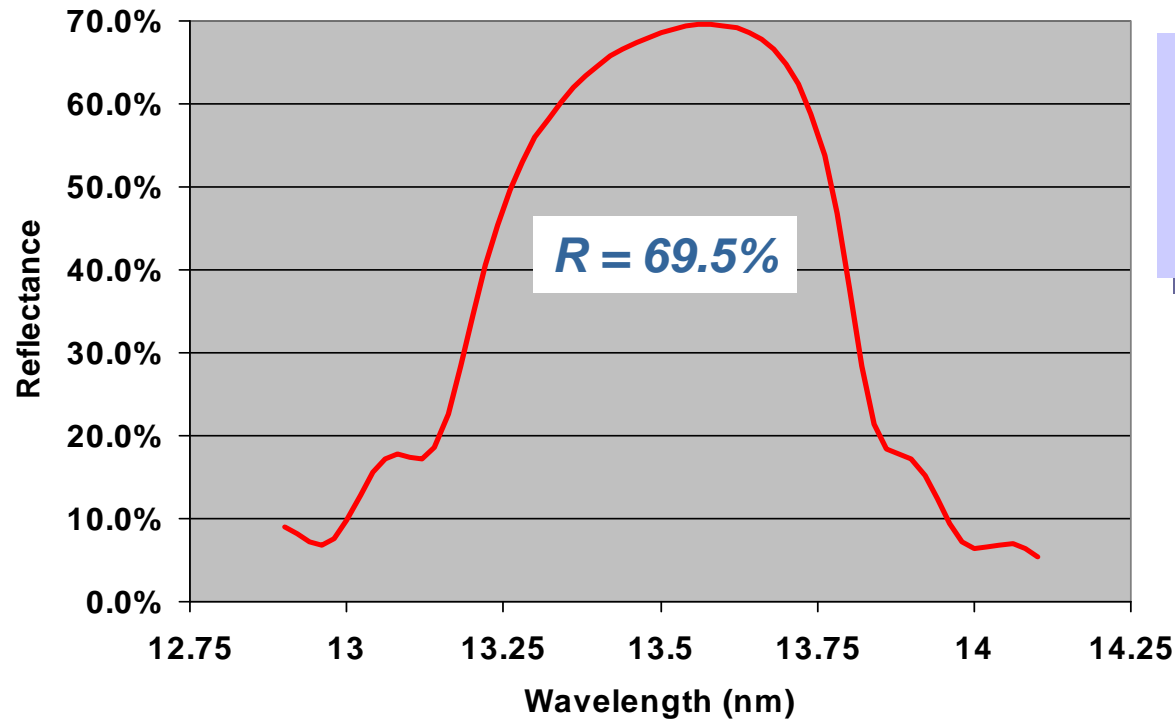
magnetron sputtering

...required for industrial coatings on large > 0.5 m substrates



Normal incidence reflectance

EUV reflectometry at PTB, Berlin, Germany



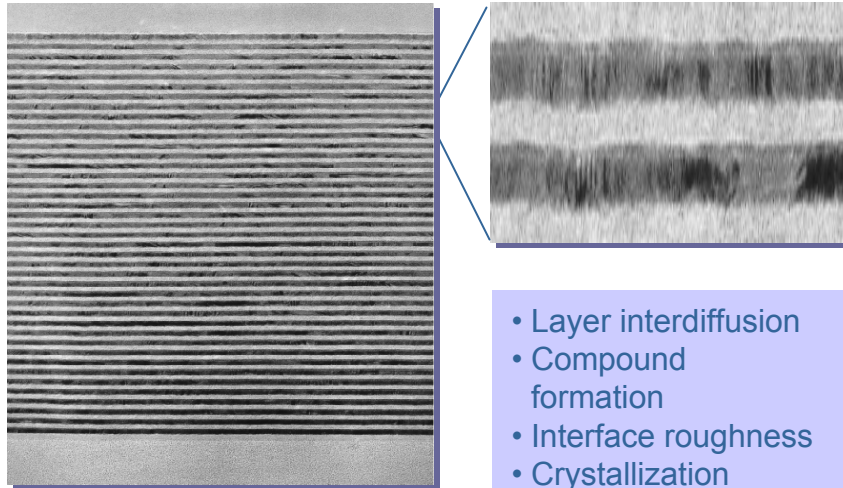
*50 periodes Mo/Si:
69.5 % @ 13.5 nm
(1.5 ° off normal, PTB)*

→ 69.5 % highest possible value for Mo/Si, but still < theoretical 75 %



Interface engineering

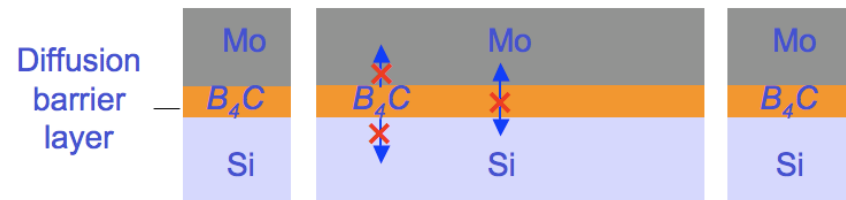
HRTEM



50 periods Mo/Si
 $d = 6.9 \text{ nm}$, $\Gamma \approx 0.4$

- Layer interdiffusion
- Compound formation
- Interface roughness
- Crystallization
- Density variations
- Void formations
- ...

Dr. F. Tichelaar, Delft University of Technology



→ Diffusion barrier layers reqd at sub-nm thickness
 → Materials & growth determined

→ **'Interface engineering'**

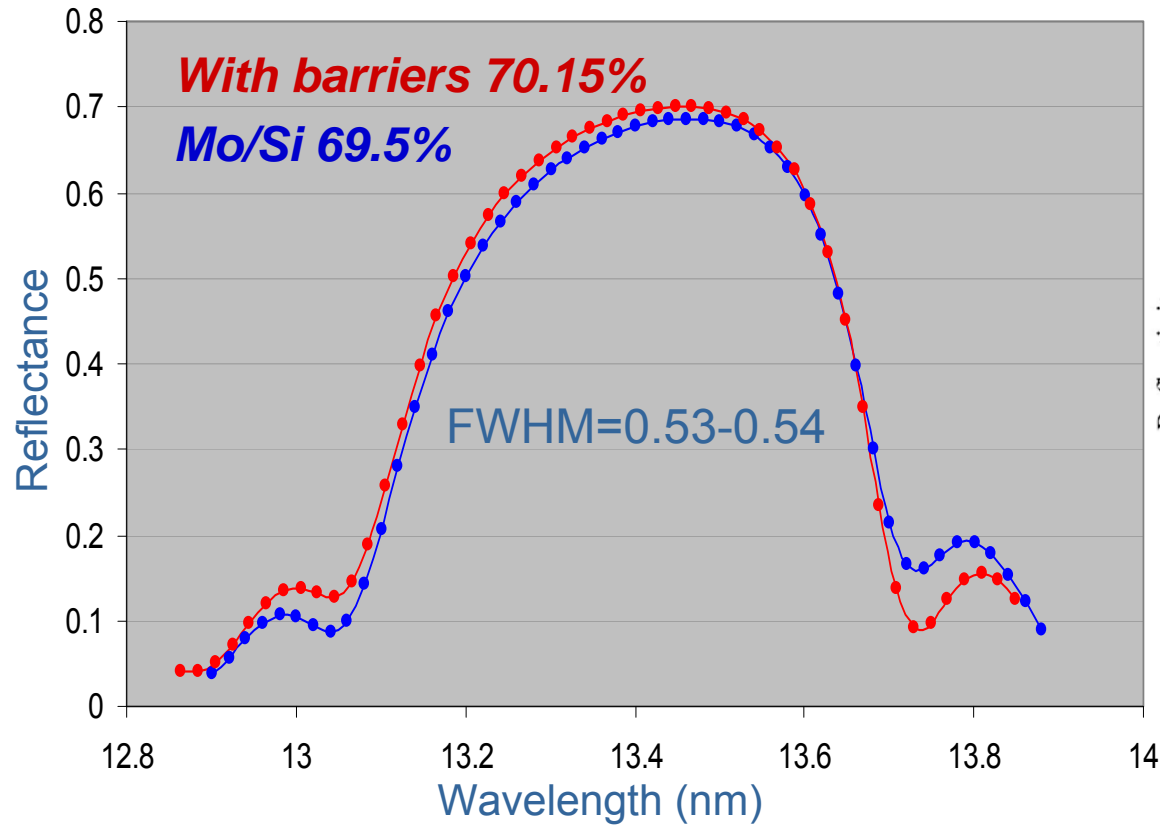
Thin barriers: prevent diffusion & enhance reflectance

Thick barriers: prevent diffusion



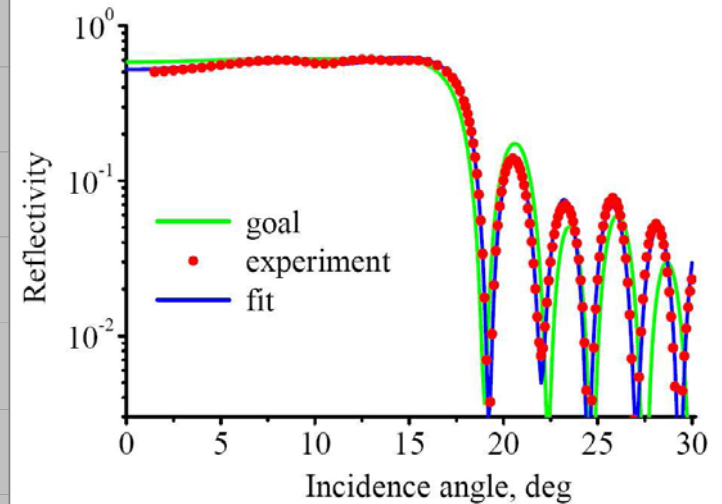
Barriers: reflectance & bandwidth

Reflectance @ 1.5 ° off-normal



A.E. Yakshin, R.W.E. van de Kruijs, et al, SPIE, Vol. 6517, 2007

*Improved angular width:
depth graded ML*



A.E. Yakshin et al, Optics Express **18**, 6957-6971 (2010)

Thin barriers enable reflectance enhancement !



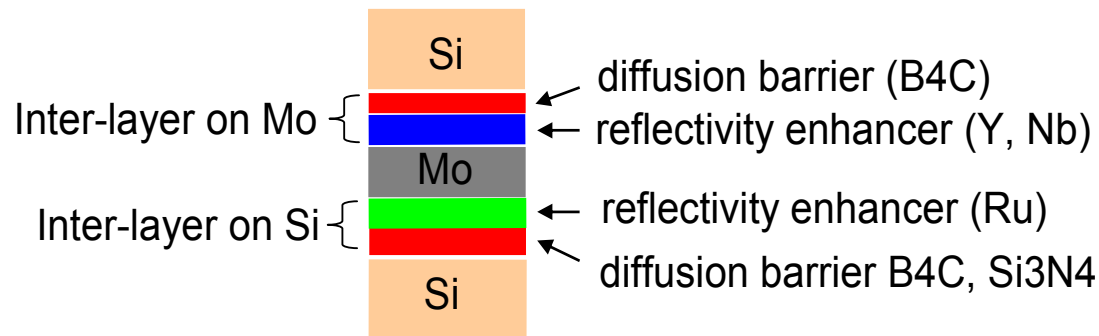


Compounded interlayer systems

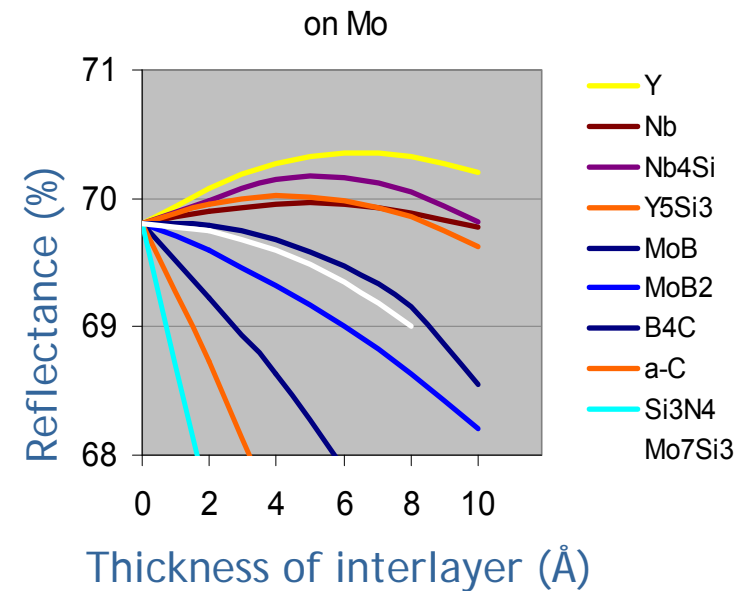
Traditionally one diffusion barrier with both favorable optical and diffusion reduction properties per interface.

Can it be functionally split: optical - diffusion ?

From bi-layer to six-layer design *



Calculated reflectance for candidate materials

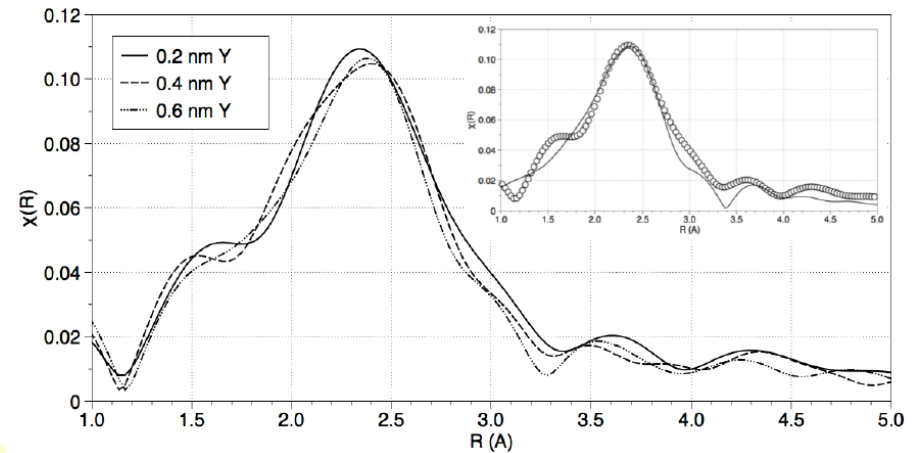
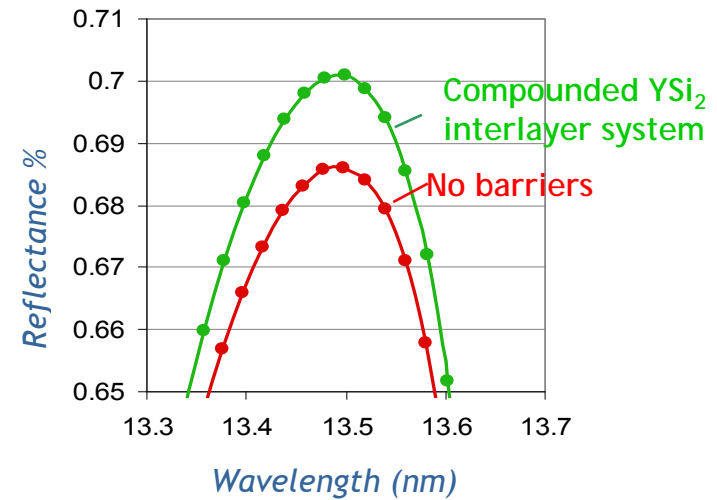
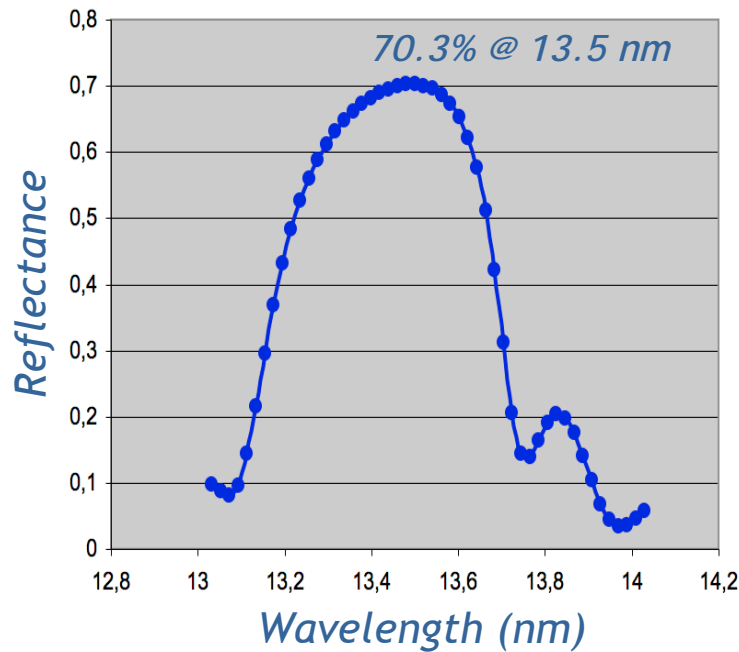


* A.E. Yakshin, et. al, Patent US 60/888,144, US, EU (2007)



Compounded interlayer systems

Can these Å-scale structures be made?



→ Sub nm interlayers can improve refractive index distribution

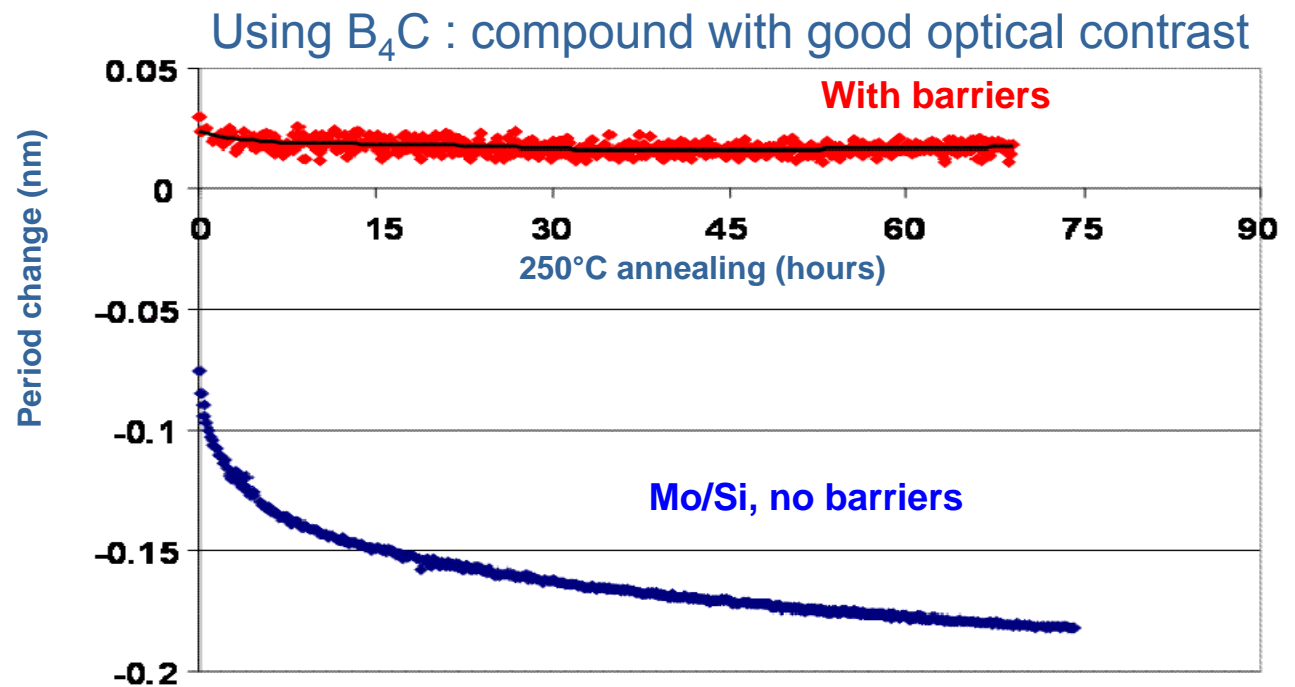
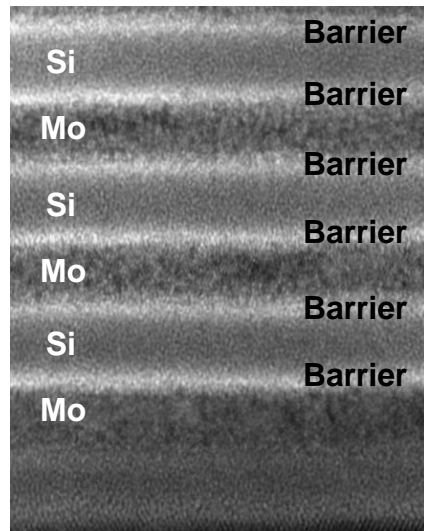
Yakshin, et al, SPIE 6517-17 (2007)

Bosgra, et al, to be submitted



Diffusion barriers for thermal stability

- 30 % radiation absorbed
- improve thermal resistance

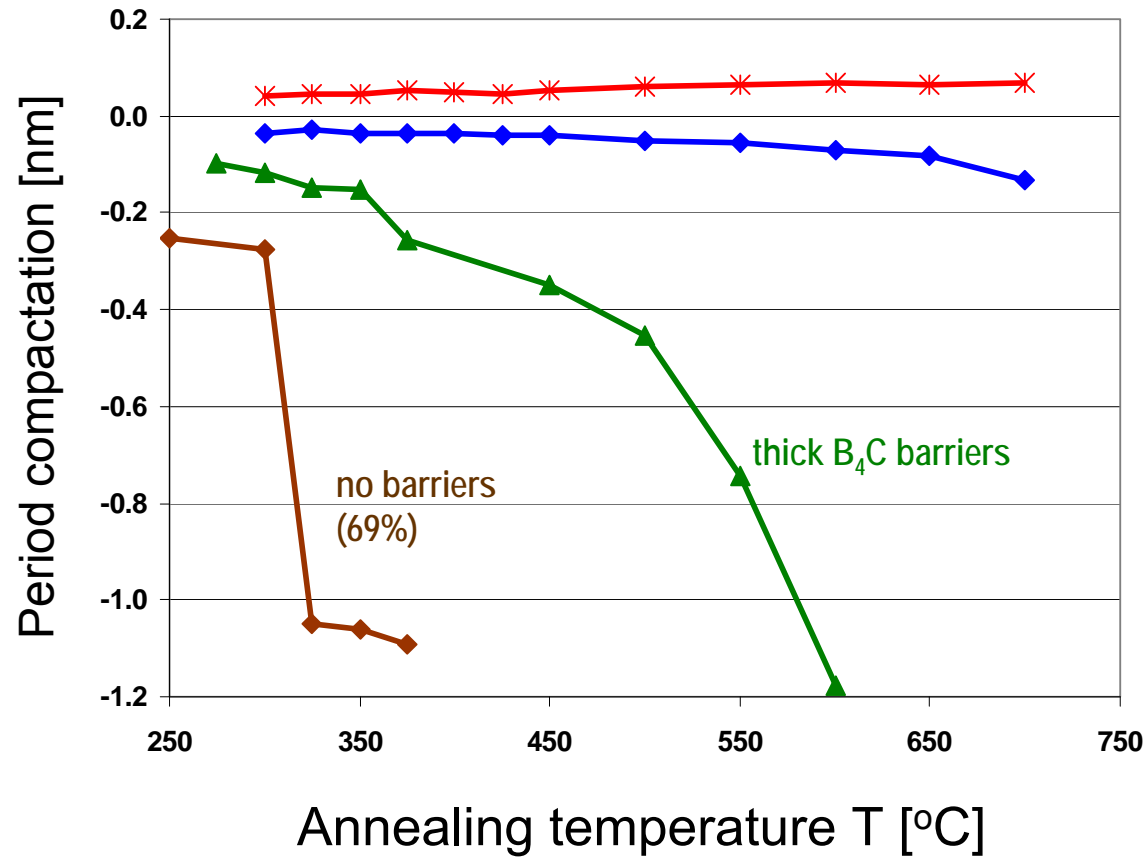


- Clear improvement, but what is actually formed?



Thermal resistance various barriers

Mo/Si multilayers with various barriers



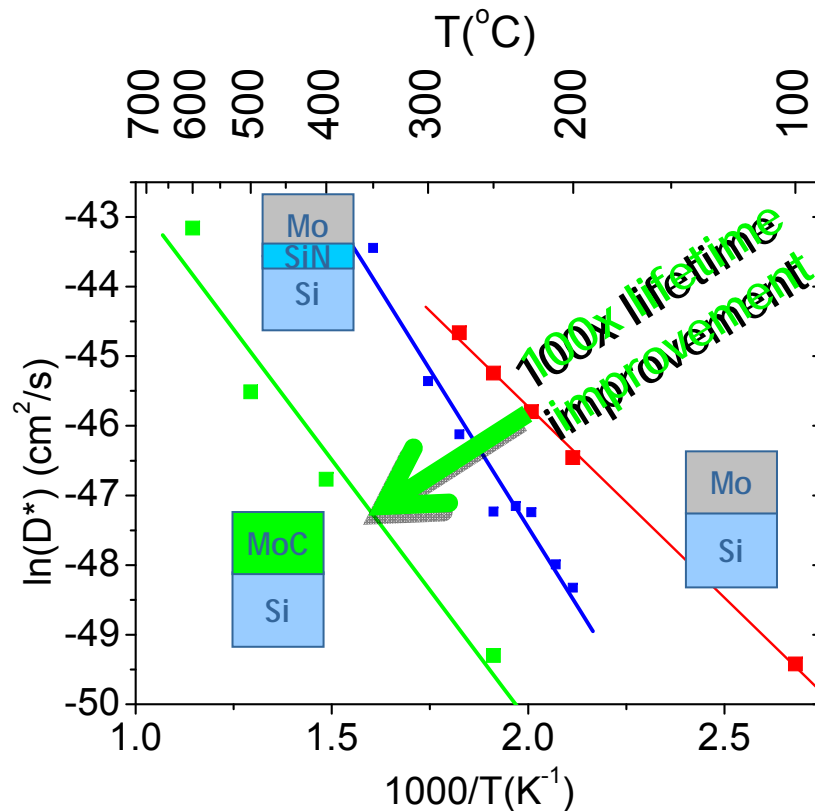
- Very good thermal stability achievable, but at the expense of reflectance



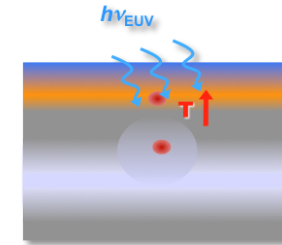
'Diffusion scaling laws'

Passivated systems and systems with diffusion barriers

Goal: study diffusion at initial stage



Diffusion, intermixing & crystallization



Arrhenius plots provide method for scaling of diffusion.

Activation energies provide information about fundamental diffusion processes.

$$D = D_0 \exp \frac{E_a}{kT}$$

Y-value D_0

Slope: E_a

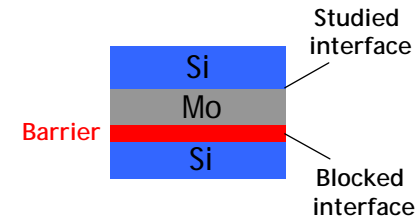
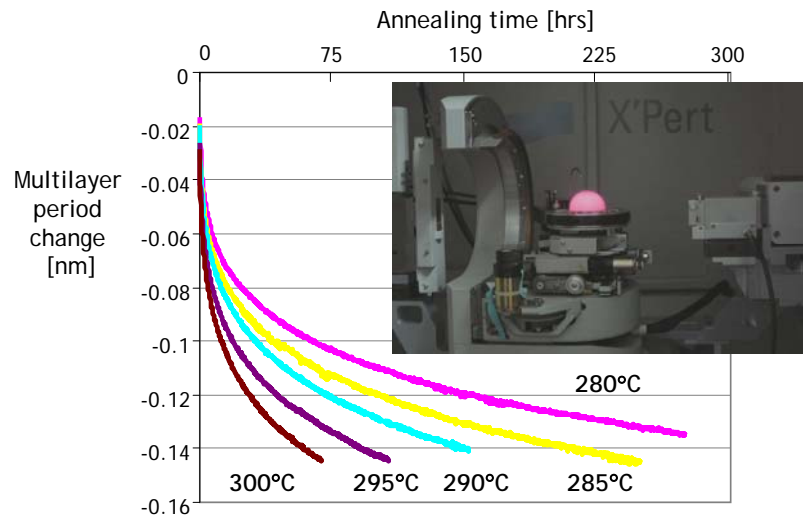
Tsarfaty, et al, JAP 105 (2009)

Bruin, et al, ASS, 10-02316R1 (2010)



Activation energy atomic scale interdiffusion

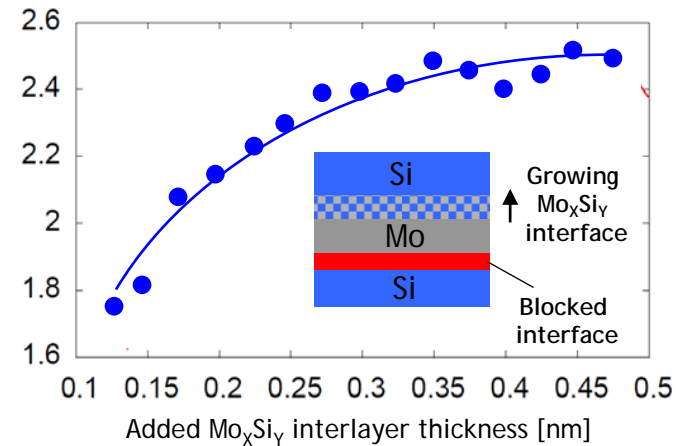
Selective analysis of interface diffusion by use of diffusion barriers



In-situ structure investigation shows temperature dependent change with sub-pm accuracy

→ Diffusion kinetics modeling reveals interdiffusion layer thickness dependent activation energy

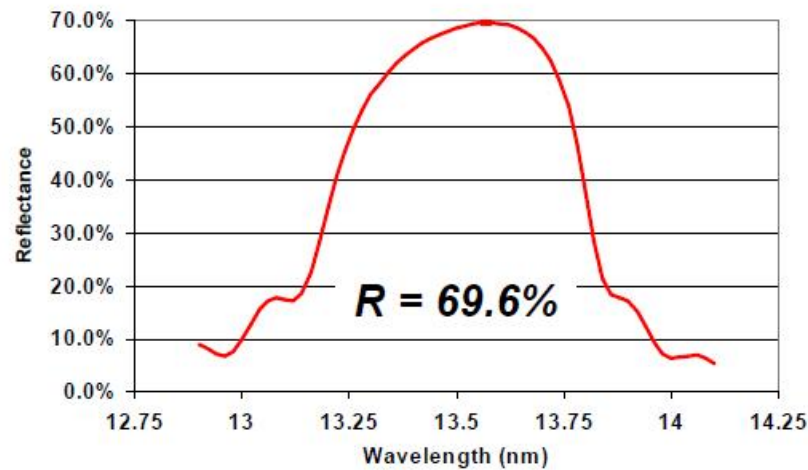
Activation energie [eV]



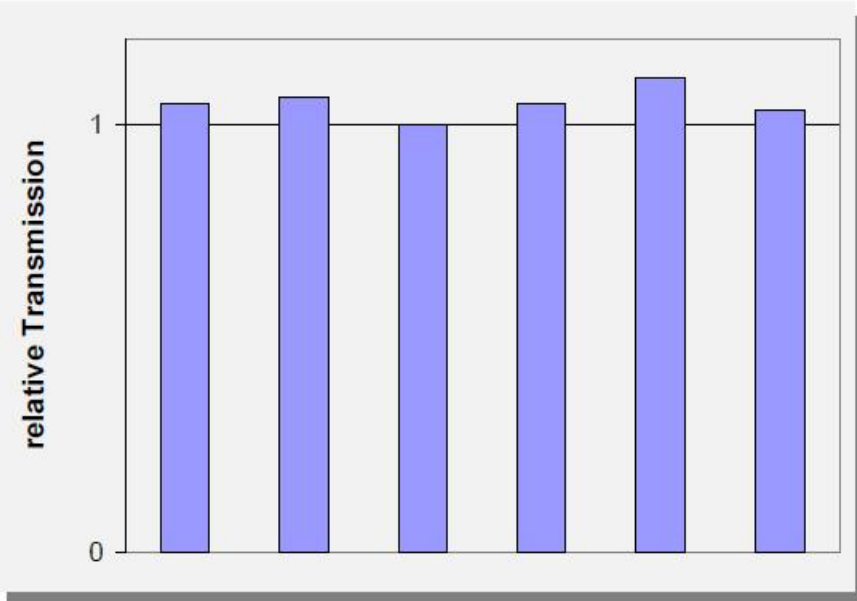
Jeroen Bosgra, Robbert vd Kruijs, Andrey Yakshin

Courtesy of Dr. Peter Kürz, Carl Zeiss SMT GmbH (EUVL symp. Kobe, 2010)

NXE:3100 – Coating reflectivity significantly increased compared to ADT



Coated at FOM, measured at PTB
ADT: ~ 64% (typical achievements)

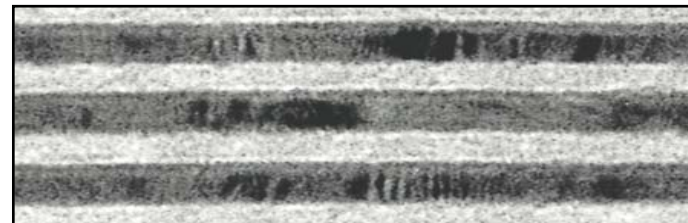
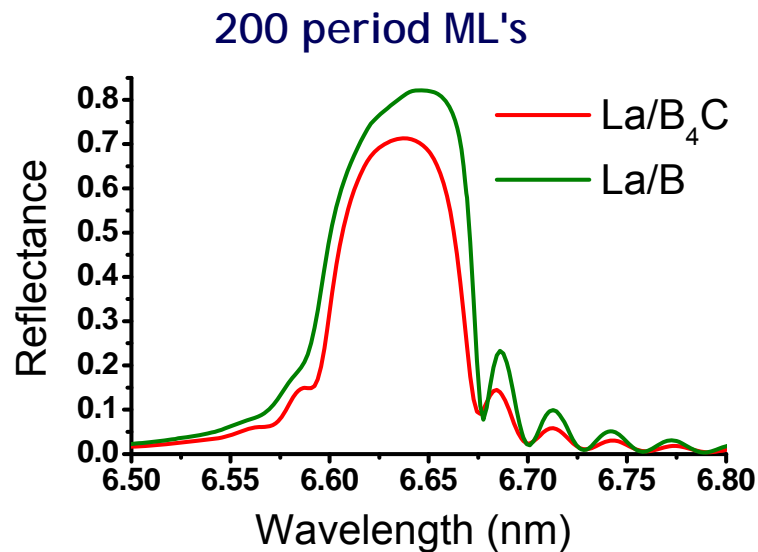


about 50% more transmission of 3100 projection optics



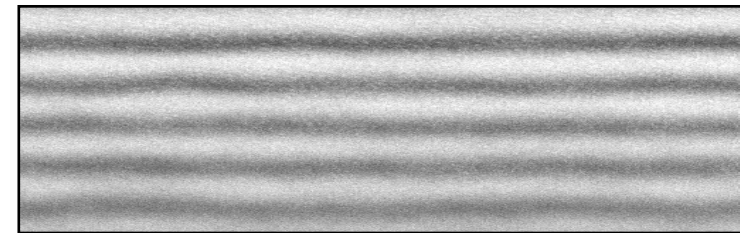
Downscaling λ to 'beyond EUV': 6.x nm

Materials choice determined by optical constants
- low absorption, high contrast



Mo/Si

La/B₄C



From 13.5 to 6.x nm:

- *“Just switch material and reduce layer thicknesses”, but*
 - ◆ *Individual layers \approx 1 nm*
 - ◆ *Effect of roughness & interdiffusion become dominant*
- Degree of difficulty increases enormously!*



Development beyond EUV coatings

New approaches to be pursued:

- *Film nucleation and layer growth*
 - ◆ *Dependence of layer growth on ad-atom energy*
 - ◆ *Kinetic Growth Manipulation (KGM)*
- *Interface control by layer passivation*
- *Multilayer analysis by He-ion microscopy*
 - ◆ *sub-nm depth resolution*



Thermodynamics @ La/B₄C interfaces

At interfaces: $7 \text{ La} + 6 \text{ B}_4\text{C} \rightarrow 4 \text{ LaB}_6 + 3 \text{ LaC}_2$ ($\Delta H = - 305.4 \text{ kJ/mole}$)

Compound	LaN	BN	LaB ₆	LaC ₂	B ₄ C	La
ΔH^{for} (kJ/mol)	-303	-255	-130	-89	-71	0
n	0.981	0.995	0.992	0.986	0.999	0.984
β (10 ⁻³)	1.420	0.894	0.853	0.996	0.528	1.075

→ Introduce stable nitrides by N⁺-ion treatment:

- Nitride formation can prevent LaB₆ and LaC₂ formation
- LaN can enhance optical contrast ^{1,2,3}

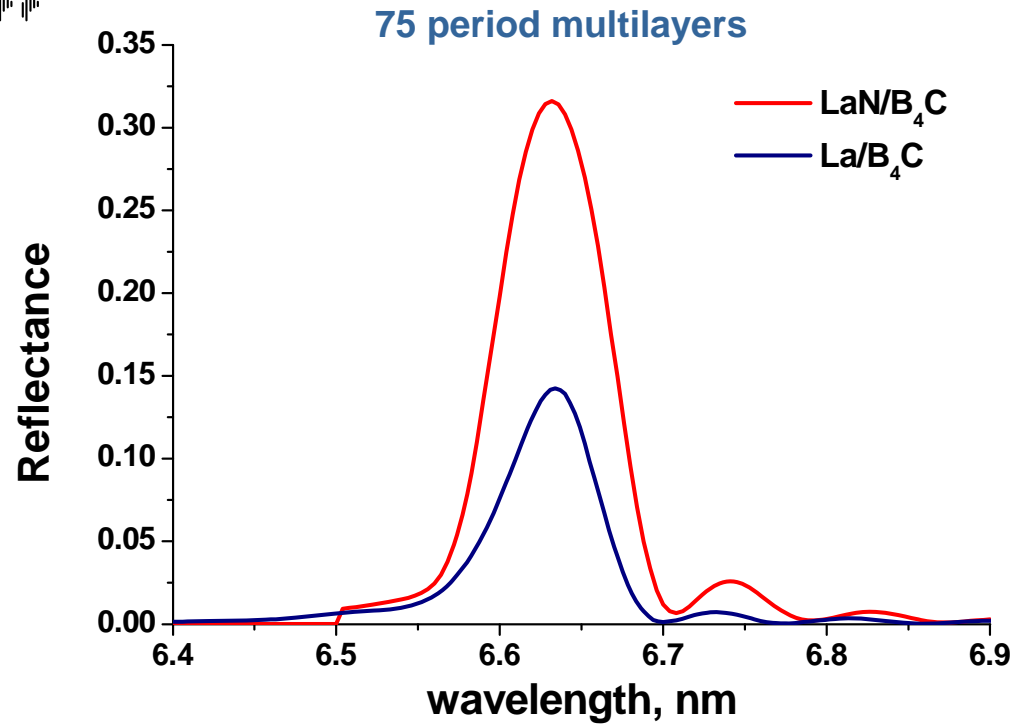
¹T. Tsarfati et al., "Reflective multilayer optics for 6.7 nm wavelength radiation sources and next generation lithography", *Thin Solid Films* 518, 5, 1365-1368 (2009)

²T. Tsarfati et al., "Nitridation and contrast of B₄C/La interfaces and multilayers" *Thin Solid Films* 518, 24, 7249-7252 (2010)

³Patent: T. Tsarfati et al., P16795DE US 61/079307 (US), DE102008040265 (Germany), priority date 16 September 2008



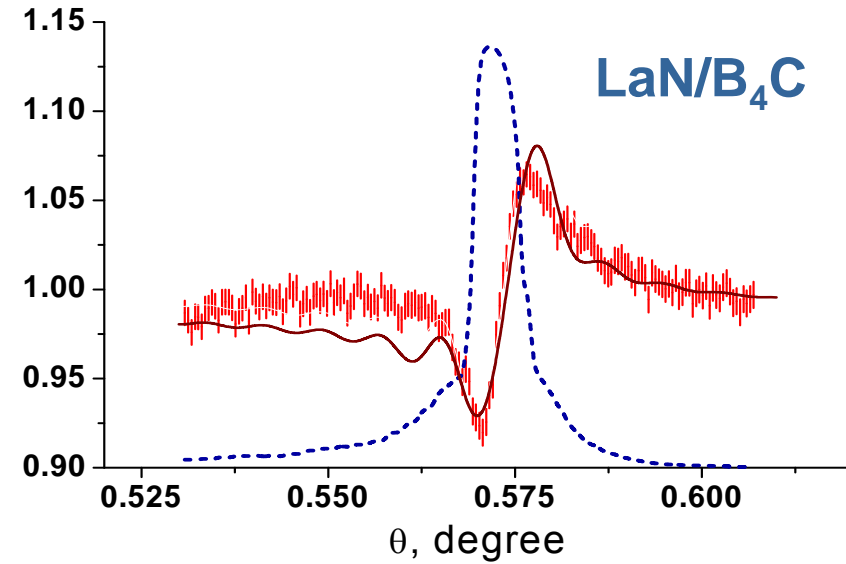
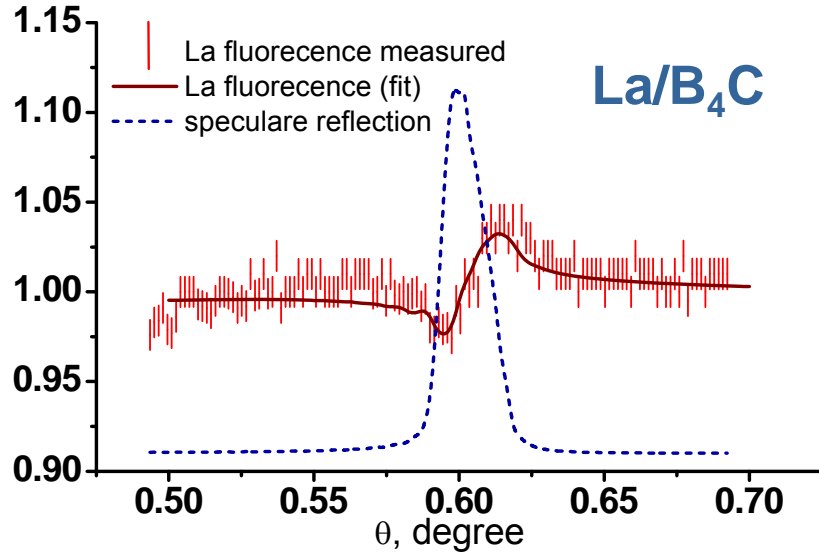
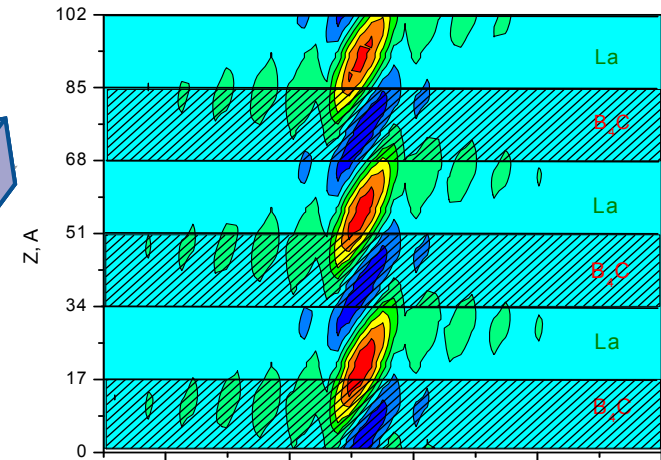
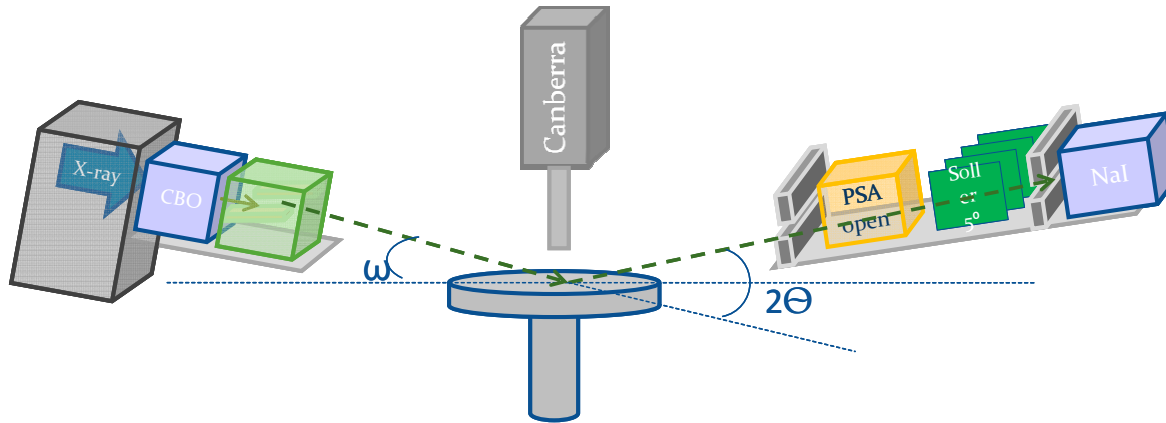
How does LaN perform in reflectance?



- Only 75 period multilayers
- Dramatic difference in maximum reflectance:
- → Better optical contrast? Better localization of materials?

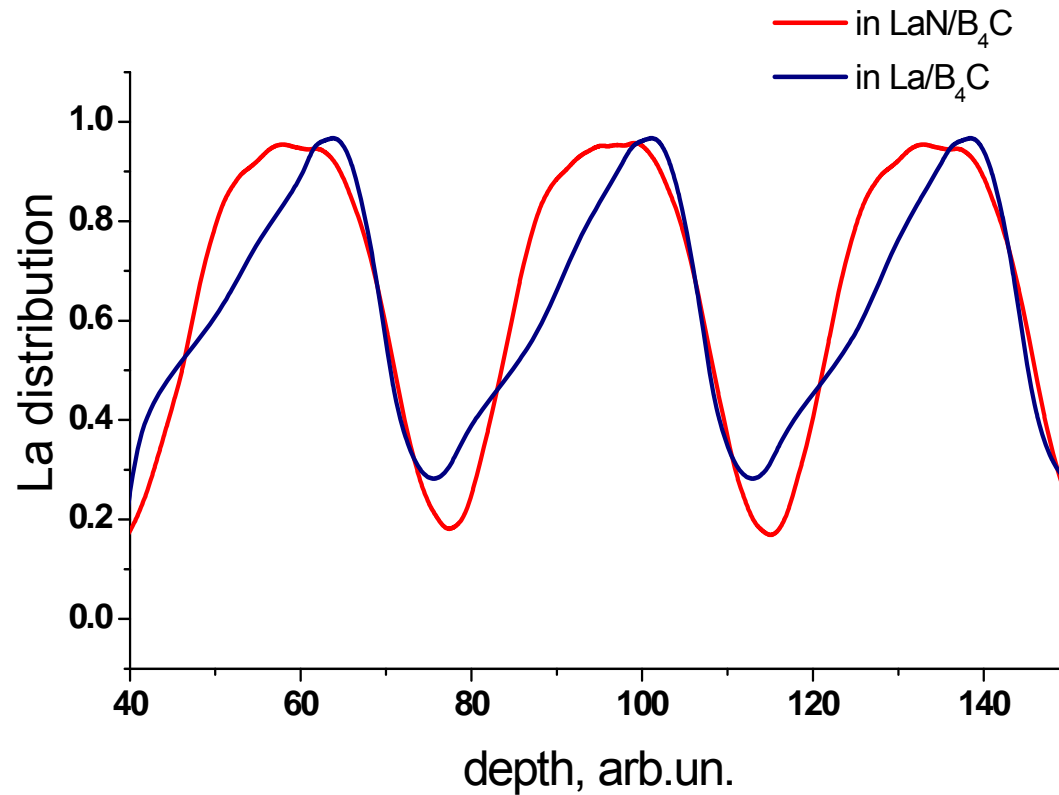


XSW: Fluorescence yield analysis





La-profile in multilayer

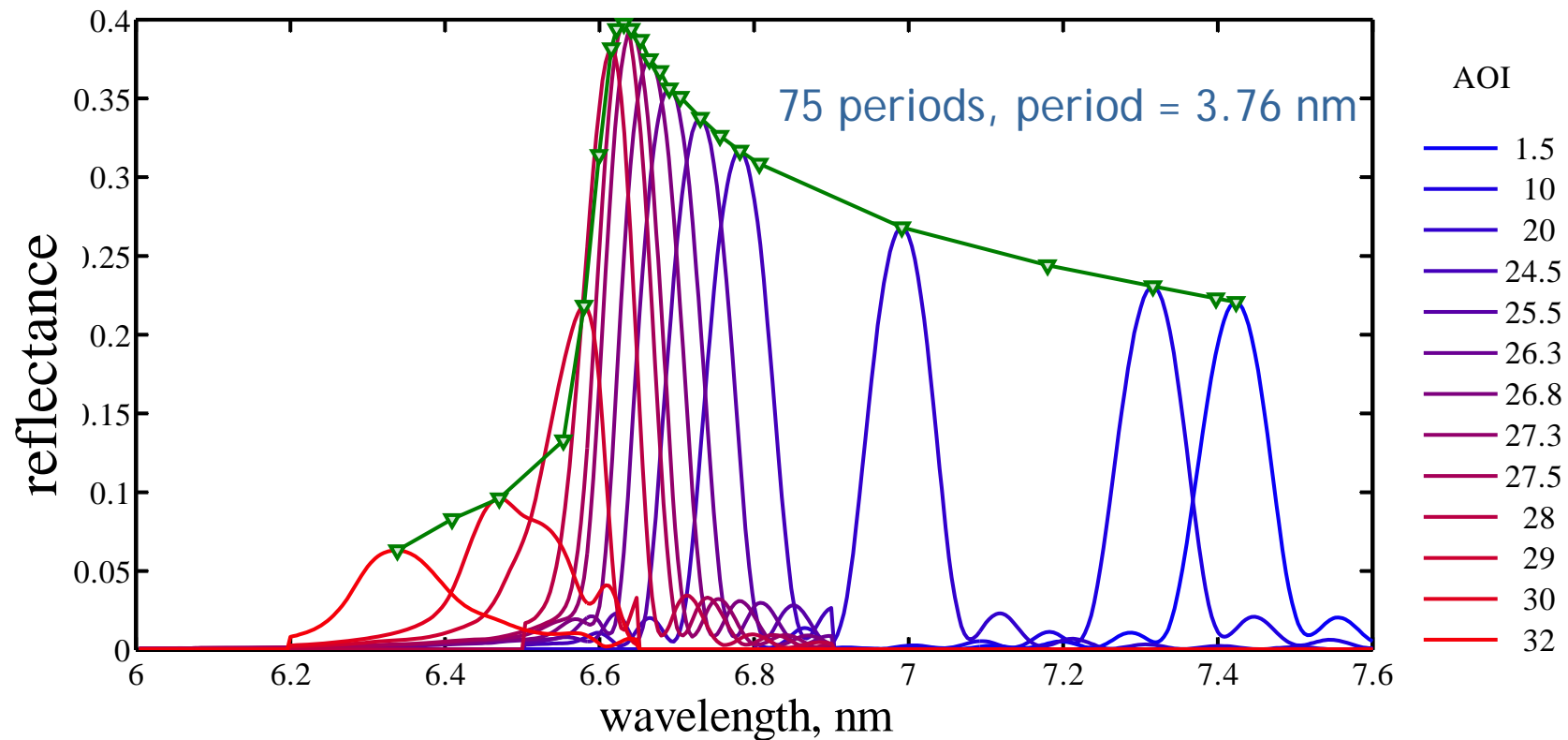


Collaboration with
Sergei Yakunin
Kurchatov Institute,
Moscow, Russia

Much better localization of La in $\text{LaN/B}_4\text{C}$
→ improved optical contrast



Approaching the B-edge....

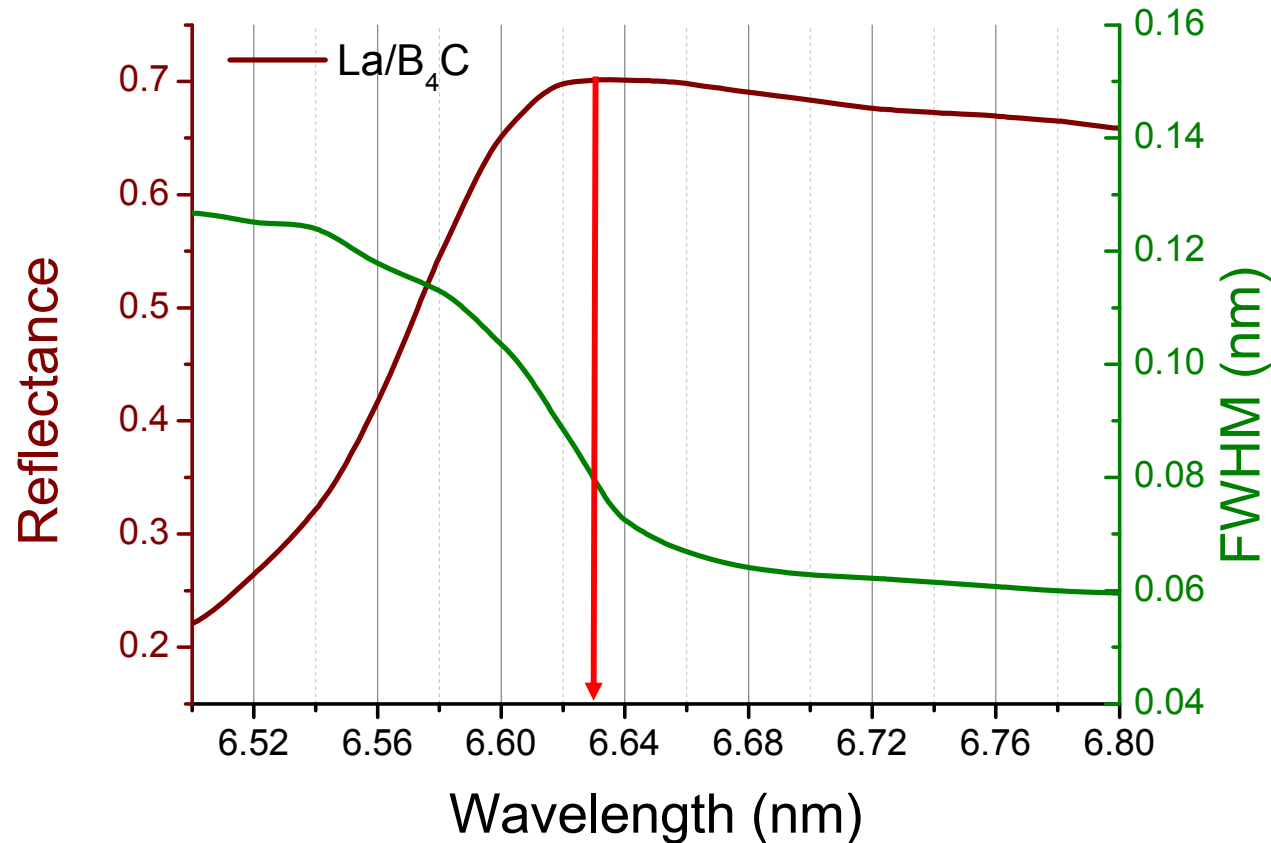


- La/B₄C ML reflectivity increases near B absorption edge
- Effect enhanced by s-polarised measurements
- Good fit obtained using experimental B optical constants (Regina Soufli and Monica Fernandez)



Approaching the B-edge....

Calculated normal incidence reflectance and band width^{1,2}

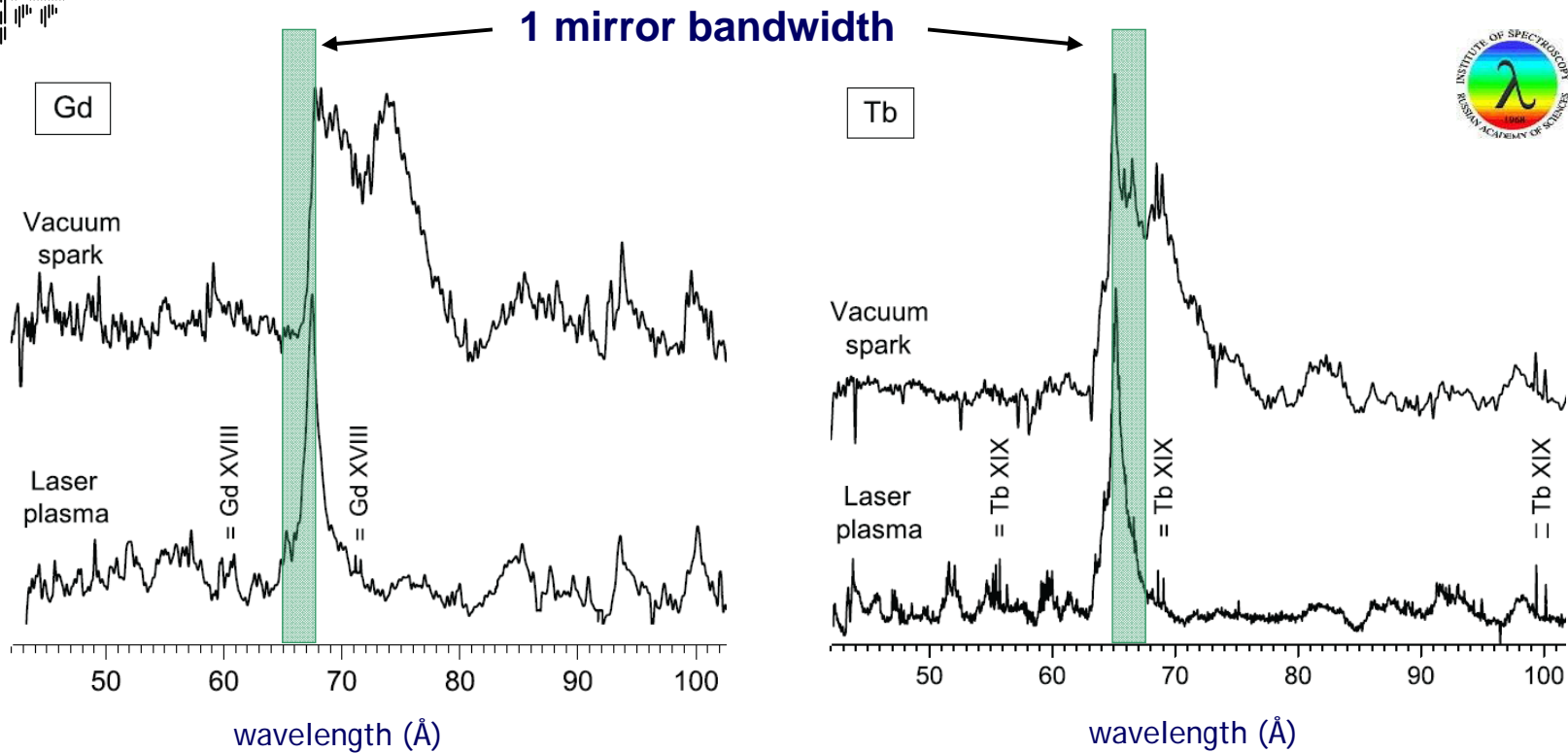


1. R. Soufli et. al., Appl. Opt., Vol. 47, 25, 2008
2. M. Fernandez-Perea et. al., J. Opt. Soc. Am. A, Vol. 24, 12, 2007

→ Optimum normal incidence reflectance and enhanced band width at 6.63 nm



Gd and Tb emission spectra



S.S. Churilov et al., Phys. Scr. 80 (2009) 045303

→ *Operational wavelength 6.x nm lithography:*

- *simultaneous optimization of source and multilayer performance*
- *together with optical design*



Summary

Multilayer performance EUV

- Reflectance 69.5 % for Mo/Si, 70.15-70.30 % with barriers
- B₄C barriers enhance thermal stability
- ML's can be stable up to 700 ° C
- 69.6% achieved on real optics, profile within spec

Beyond EUV or 6.x nm

- Passivation of interfaces → improved optical contrast
- Focus research on LaN/B₄C
- Enhanced ML performance near B-edge
- Optimum wavelength depends on multilayer, source and optical design



Acknowledgements

Coworkers at  and  and  **ASML**

The team at  Berlin for reflectometry

Thank you!

Research programs: XMO, CP3E, ACHIEVE, EXEPT

